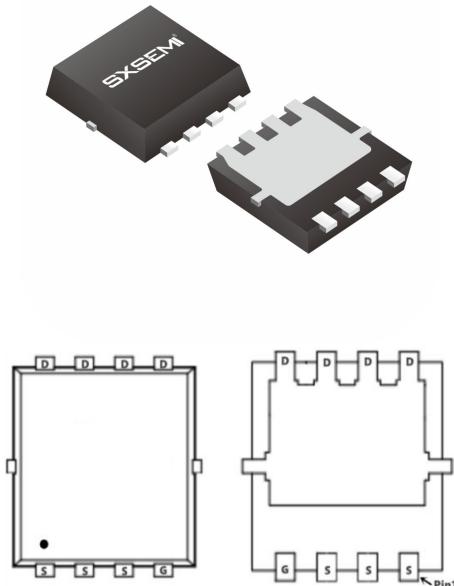


## Description

The SX80N04DF uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

## PDFN3\*3-8L

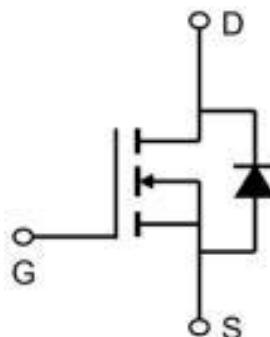


## General Features

$V_{DS} = 40V$   $I_D = 80A$   
 $R_{DS(ON)} < 6.5m\Omega$  @  $V_{GS}=10V$

## Application

Battery protection  
Load switch  
Uninterruptible power supply



## Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

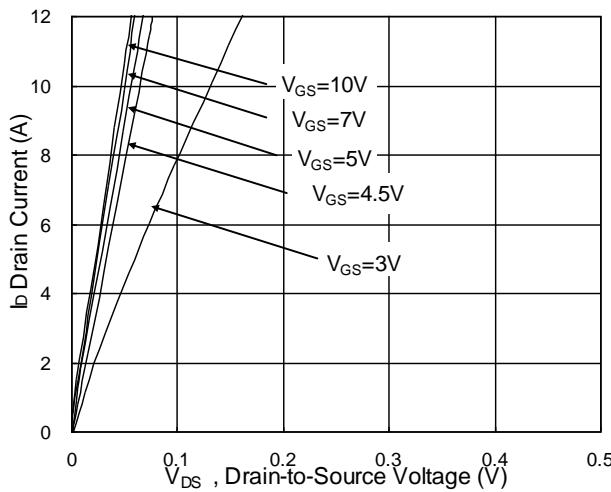
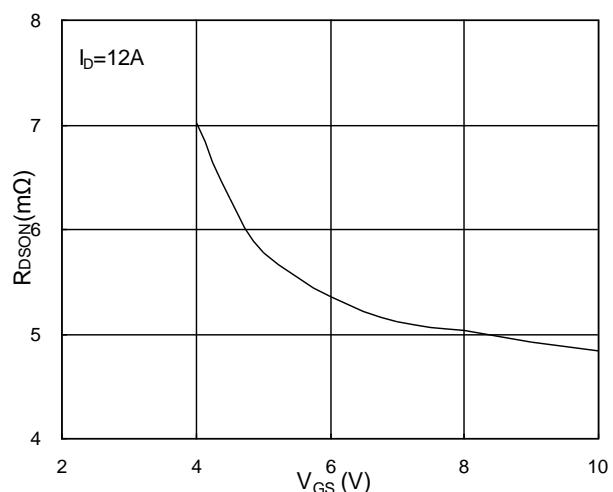
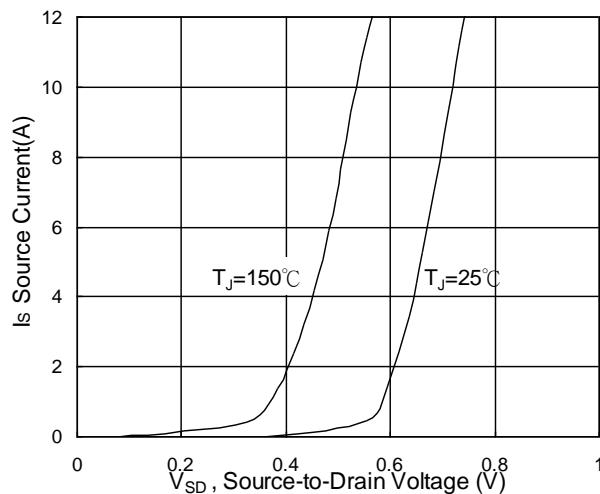
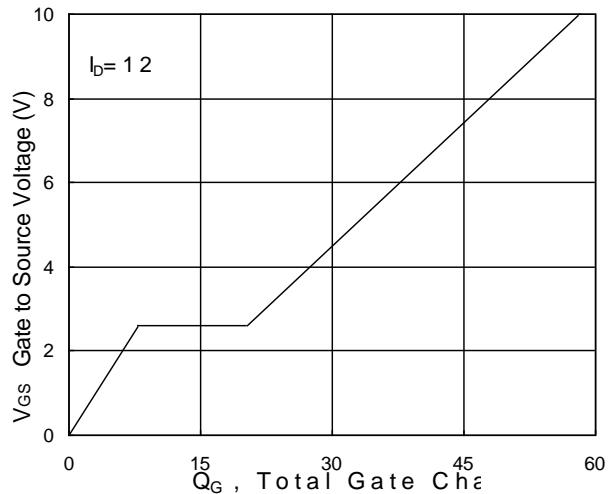
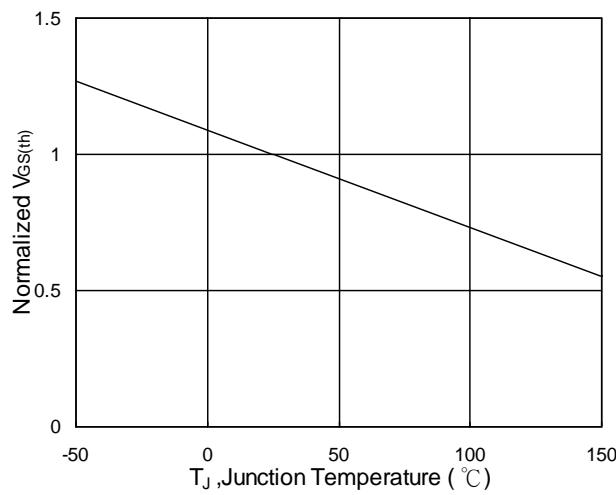
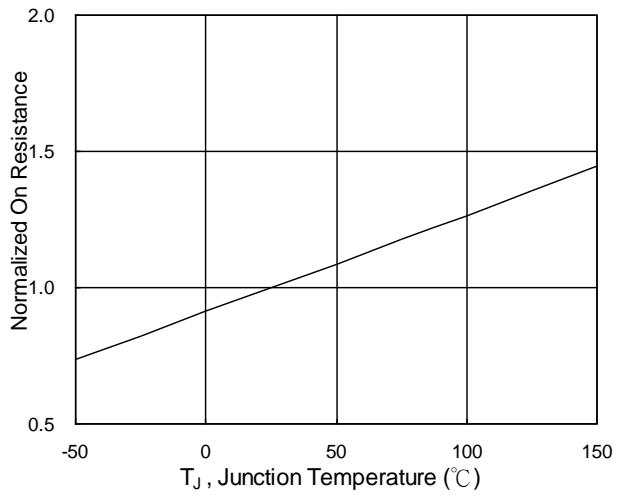
Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_c=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	80	A
$I_D@T_c=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	58	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	150	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	110.5	mJ
$I_{AS}$	Avalanche Current	47	A
$P_d@T_c=25^\circ C$	Total Power Dissipation <sup>4</sup>	52.1	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C
$R_{eJA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	62	°C/W
$R_{eJC}$	Thermal Resistance Junction-Case <sup>1</sup>	2.4	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

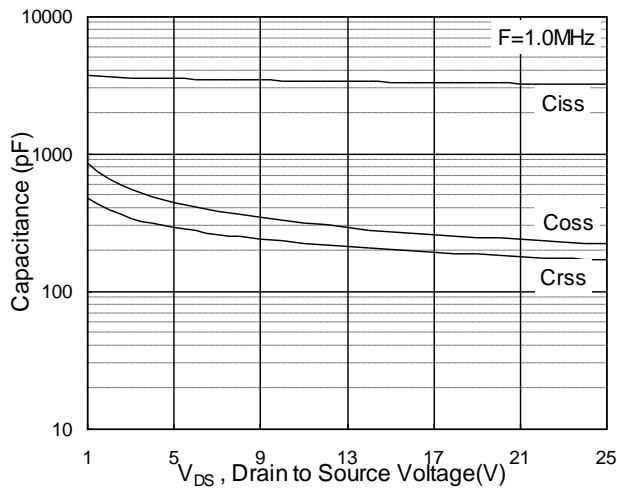
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	40	---	---	V
$\Delta BVDSS/\Delta T_J$	BVDSS Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.034	---	$\text{V}/^\circ\text{C}$
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10\text{V}$ , $I_D=15\text{A}$	---	4.8	6.5	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=12\text{A}$	---	7.2	9	
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu\text{A}$	1.0	---	2.5	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	-5.84	---	$\text{mV}/^\circ\text{C}$
IDSS	Drain-Source Leakage Current	$V_{DS}=32\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{DS}=32\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA
gfs	Forward Transconductance	$V_{DS}=5\text{V}$ , $I_D=15\text{A}$	---	27	---	S
R <sub>g</sub>	Gate Resistance	$V_{DS}=0\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	1.4	---	$\Omega$
Q <sub>g</sub>	Total Gate Charge (4.5V)	$V_{DS}=20\text{V}$ , $V_{GS}=4.5\text{V}$ , $I_D=12\text{A}$	---	28	---	nC
Qgs	Gate-Source Charge		---	7.85	---	
Qgd	Gate-Drain Charge		---	12.5	---	
Td(on)	Turn-On Delay Time	$V_{DD}=15\text{V}$ , $V_{GS}=10\text{V}$ , $R_G=3.3\Omega$ , $I_D=1\text{A}$	---	20.2	---	ns
T <sub>r</sub>	Rise Time		---	11.8	---	
Td(off)	Turn-Off Delay Time		---	84.8	---	
T <sub>f</sub>	Fall Time		---	8.6	---	
Ciss	Input Capacitance	$V_{DS}=15\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	3354	---	pF
Coss	Output Capacitance		---	275	---	
Crss	Reverse Transfer Capacitance		---	204	---	
IS	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	75	A
ISM	Pulsed Source Current <sup>2,5</sup>		---	---	150	A
VSD	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0\text{V}$ , $I_S=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V

**Note :**

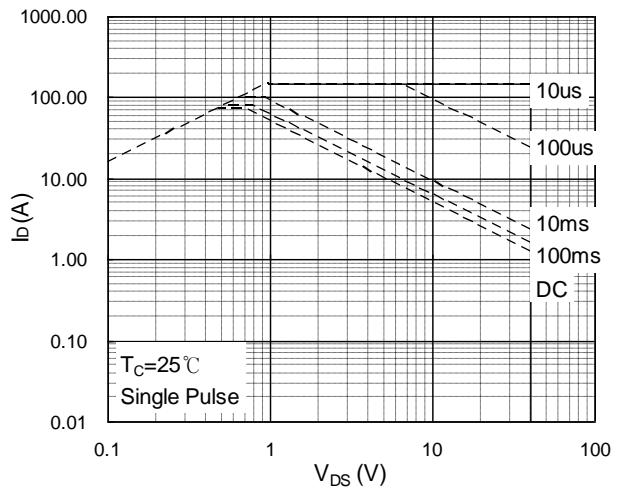
- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3、The EAS data shows Max. rating . The test condition is  
 $V_{DD}=25\text{V}$ ,  $V_{GS}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{AS}=47\text{A}$  4 、 The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5、The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

**Typical Characteristics****Fig.1 Typical Output Characteristics****Fig.2 On-Resistance vs. G-S Voltage****Fig.3 Forward Characteristics Of Reverse****Fig.4 Gate-Charge Characteristics****Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$** **Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**

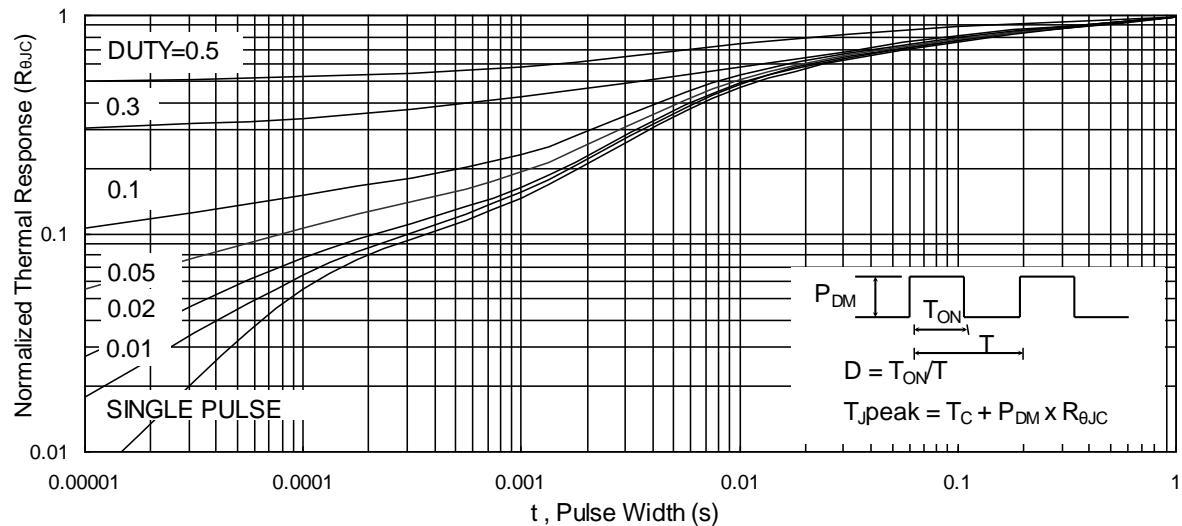
### Typical Characteristics



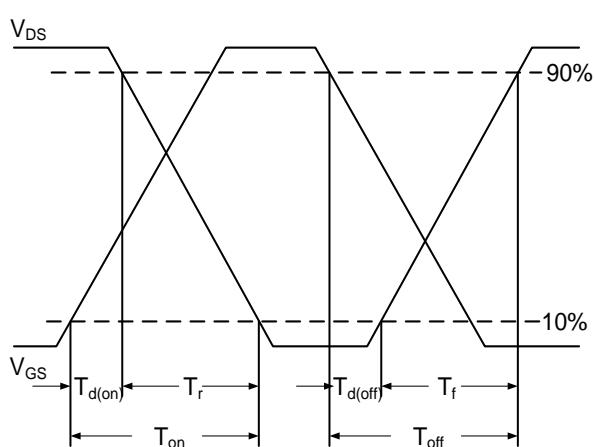
**Fig.7 Capacitance**



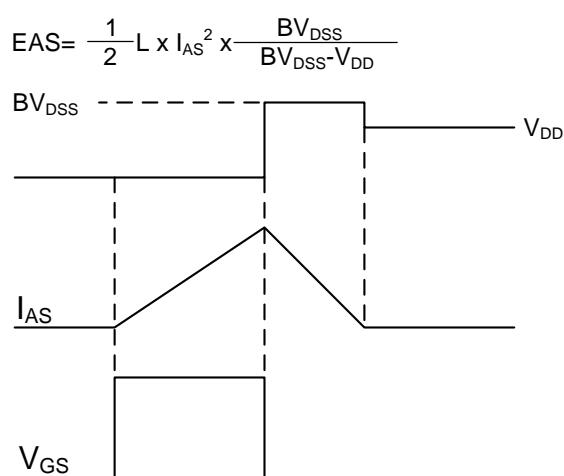
**Fig.8 Safe Operating Area**



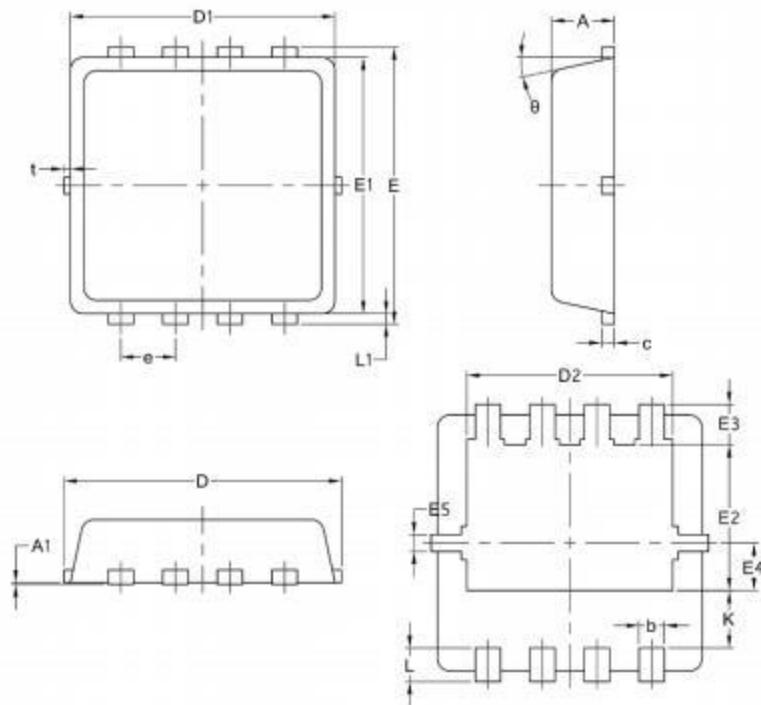
**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Wave**

**MOSFET Package Mechanical Data-PDFN3\*3-8L-JQ Single**

Symbol	Common mm		
	Mim	Nom	Max
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.30	3.45
D1	3.00	3.15	3.25
D2	2.29	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.59	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	0	0.075	0.13
Φ	10	12	14

**Package Marking and Ordering Information**

Product ID	Pack	Marking	Qty(PCS)
TAPING	PDFN3*3-8L		5000